

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	227		2
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		3
		105	L2	
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		4
		105	L3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	257		5
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		6
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		7
		105	L4	
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		8
		105	L5	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	257		9
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		10
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		11
		105	L6	
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		12
		105	L7	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	227		13
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		14
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	15

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

2277 µm

Version 1.2.20.35

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